

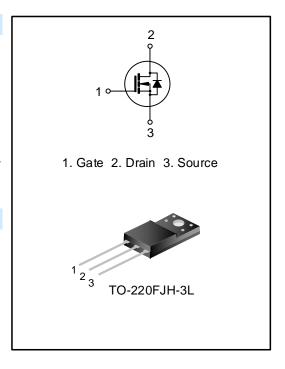
11A, 650V SUPER JUNCTION MOS POWER TRANSISTOR

DESCRIPTION

SVSP11N65AFJHD2 is an N-channel enhancement mode high voltage power MOSFETs produced using Silan's super junction MOS technology. It achieves low conduction loss and switching losses. It leads the design engineers to their power converters with high efficiency, high power density, and superior thermal behavior. Furthermore, it's universal applicable, for example, it is suitable for hard and soft switching topologies etc.

FEATURES

- 11A, 650V, $R_{DS(on)(typ.)}$ =0.33 $\Omega@V_{GS}$ =10V
- New revolutionary high voltage technology
- Ultra low gate charge
- Enhanced avalanche capability
- Extreme dv/dt rated
- High peak current capability



ORDERING INFORMATION

Part No.	Package	Marking	Hazardous substance control	Packing Type
SVSP11N65AFJHD2	TO-220FJH-3L	P11N65FJH	Halogen free	Tube

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ABSOLUTE MAXIMUM RATINGS (UNLESS OTHERWISE NOTED, TJ=25°C)

Characteristics		Symbol	Ratings	Unit	
Drain-Source Voltage		V_{DS}	650	V	
Gate-Source Voltage		V_{GS}	±30	V	
Drain Current	T _C =25°C		11	Α	
Drain Current	T _C =100°C	I _D	7	А	
Drain Current Pulsed		I _{DM}	44	Α	
Power Dissipation(T _C =25°C) -Derate above 25°C		р	35	W	
		P_D	0.28	W/°C	
Single Pulsed Avalanche Energy (Note 1)		E _{AS}	250	mJ	
Reverse diode dv/dt (Note 2)		dv/dt	15	V/ns	
MOSFET dv/dt ruggedness (Note 3)		dv/dt	50	V/ns	
Operation Junction Temperature Range		TJ	-55 ∼ +150	°C	
Storage Temperature Range		T _{stg}	-55∼+150	°C	

THERMAL CHARACTERISTICS

Characteristics		Symbol	Ratings	Unit
Thermal Resistance, Junction-to-Case		$R_{ heta JC}$	3.57	°C/W
Thermal Junction-to-Ambient	Resistance,	$R_{ heta JA}$	62.5	°C/W

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ELECTRICAL CHARACTERISTICS (UNLESS OTHERWISE NOTED, T_j=25°C)

Characteristics	Symbol	Test conditions	Min.	Тур.	Max.	Unit
Drain -Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	650			V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =650V, V _{GS} =0V			1.0	μA
Gate-Source Leakage Current	I _{GSS}	$V_{GS}=\pm30V$, $V_{DS}=0V$			±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}$, $I_{D}=250\mu A$	2.0		4.0	V
Static Drain- Source on State Resistance	R _{DS(on)}	V _{GS} =10V, I _D =5.5A		0.33	0.4	Ω
Gate resistance	R_g	f=1MHz		5.2		Ω
Input Capacitance C _{iss}		(41411) (0) (632		
Output Capacitance	Coss	f=1MHz, V _{GS} =0V, - V _{DS} =100V		37		pF
Reverse Transfer Capacitance	C _{rss}			2.3		
Turn-on Delay Time	t _{d(on)}	$-$ V _{DD} =325V, V _{GS} =10V, R _G =24 Ω , $-$ I _D =11A		12		- ns
Turn-on Rise Time	t _r			35		
Turn-off Delay Time	t _{d(off)}			64		
Turn-off Fall Time	t _f	(Note 4,5)		31		
Total Gate Charge	Qg	\\ 500\\\\ a\\\		23		
Gate-Source Charge	Q _{gs}	V _{DD} =520V, V _{GS} =10V, I _D =11A		5.3		nC
Gate-Drain Charge	Q_{gd}	(Note 4,5)		11		

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

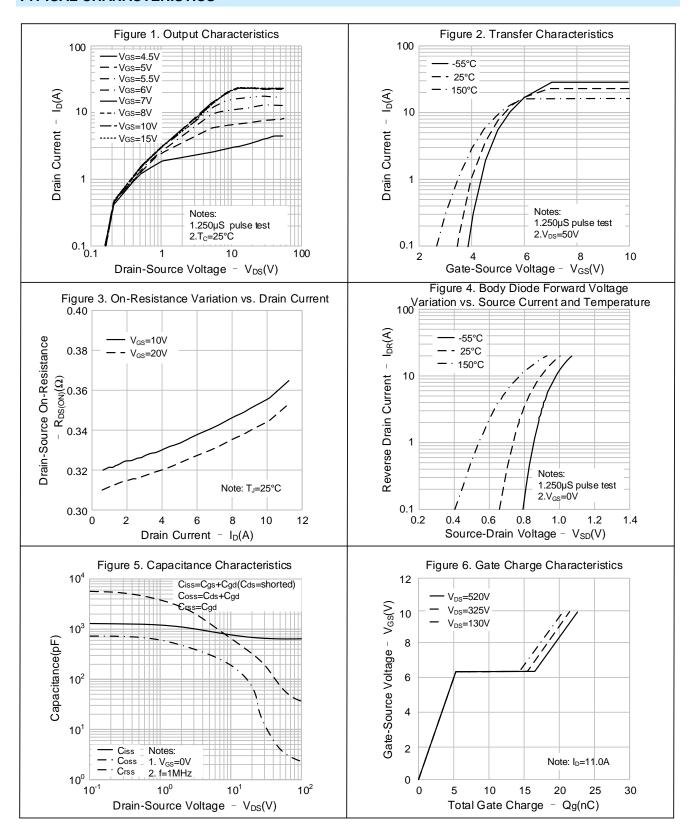
Characteristics	Symbol	Test conditions	Min.	Тур.	Max.	Unit
Continuous Source Current	Is	Integral Reverse P-N Junction			11	۸
Pulsed Source Current	I _{SM}	Diode in the MOSFET			44	А
Diode Forward Voltage	V _{SD}	I _S =11A, V _{GS} =0V			1.4	V
Reverse Recovery Time	T _{rr}	I _S =11A, V _{GS} =0V,		361		ns
Reverse Recovery Charge	Qrr	dI _F /dt=100A/μs (Note 4)		3.9		μC

Notes:

- 1. L=79mH, I_{AS}=2.4A, V_DD=100V, R_G=25 Ω , starting temperature T_J=25°C;
- $V_{DS}=0~400V$, $I_{SD}<=11A$, $T_{J}=25$ °C;
- V_{DS}=0~480V; 3.
- 4. Pulse Test: Pulse width ≤300µs,Duty cycle≤2%;
- Essentially independent of operating temperature. 5.

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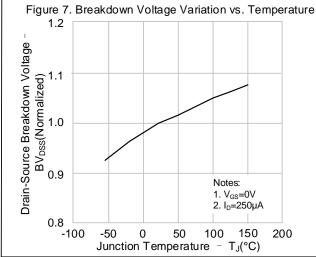
TYPICAL CHARACTERISTICS

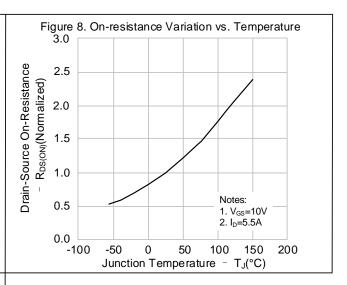


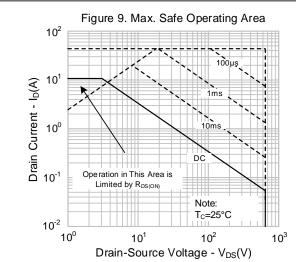
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TYPICAL CHARACTERISTICS (CONTINUED)





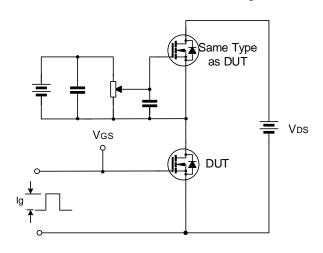


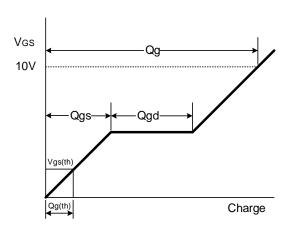
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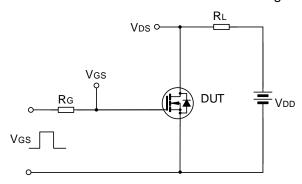
TYPICAL TEST CIRCUIT

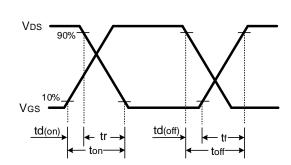
Gate Charge Test Circuit & Waveform



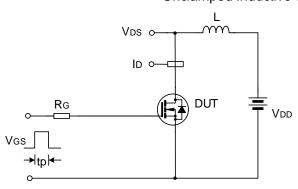


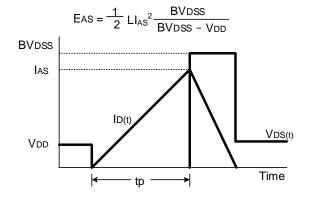
Resistive Switching Test Circuit & Waveform





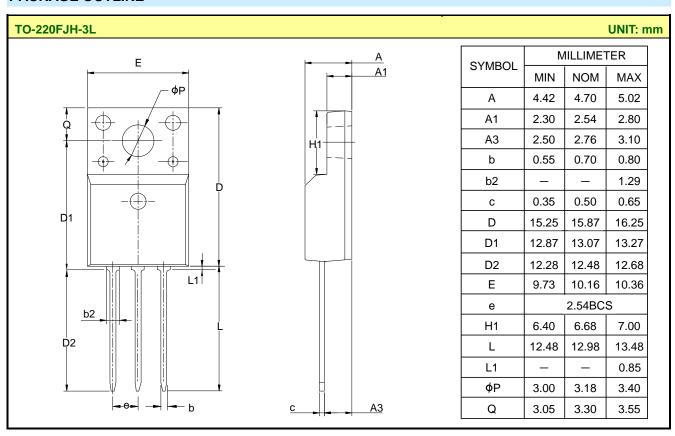
Unclamped Inductive Switching Test Circuit & Waveform







PACKAGE OUTLINE





MOS DEVICES OPERATE NOTES:

Electrostatic charges may exist in many things. Please take following preventive measures to prevent effectively the MOS electric circuit as a result of the damage which is caused by discharge:

- The operator must put on wrist strap which should be earthed to against electrostatic.
- Equipment cases should be earthed.
- All tools used during assembly, including soldering tools and solder baths, must be earthed.
- MOS devices should be packed in antistatic/conductive containers for transportation.

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- Silan reserves the right to make changes of this instruction without notice.
- 2. Customers should obtain the latest relevant information when purchasing and should verify whether such information is latest and complete. Please read this instruction and application manual and related materials carefully before using products, including the circuit operation precautions, etc.
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First release

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